



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC017N04NM5	Issued	24. February 2022
MA#	MA005708672		
Package	PG-TDSON-8-36	Weight*	115.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.110	0.96	0.96	9593	9593
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		422	
	non noble metal	copper	7440-50-8	48.769	42.15	42.20	421355	421904
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		717	
	plastics	epoxy resin	-	6.556	5.66		56644	
	inorganic material	silicondioxide	60676-86-0	34.856	30.11	35.84	301146	358507
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	12023	12023
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1675	1675
solder	non noble metal	tin	7440-31-5	0.030	0.03		257	
	noble metal	silver	7440-22-4	0.037	0.03		322	
	non noble metal	lead	7439-92-1	1.422	1.23	1.29	12285	12864
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	non noble metal	copper	7440-50-8	17.131	14.80	14.81	148012	148204
clip plating	noble metal	silver	7440-22-4	1.059	0.92	0.92	9151	9151
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.57	2.57	25672	25706
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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